

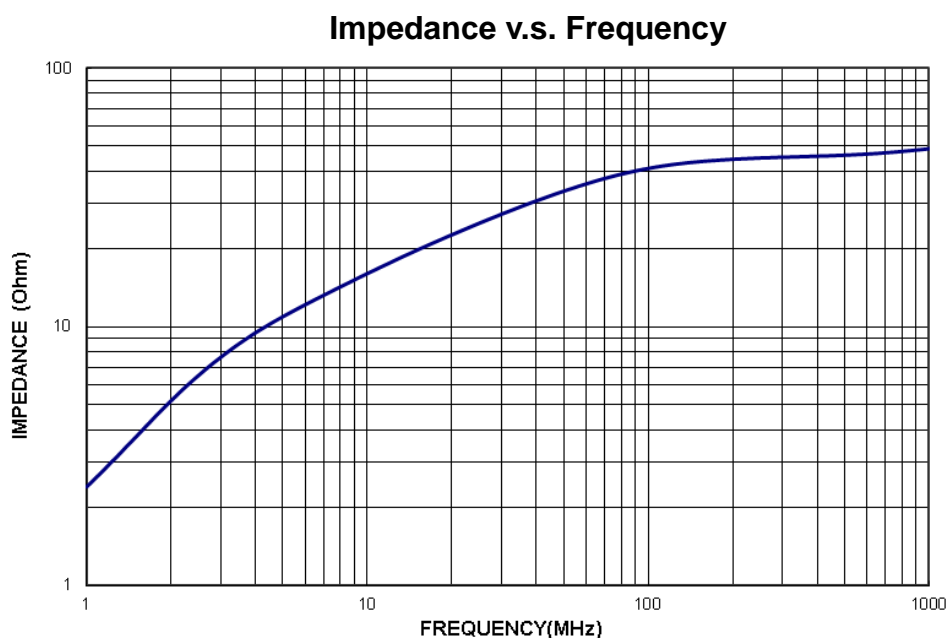
4. General Specification:

- (a) Operating Temp. : -40°C to +125°C (Including self - temperature rise).
- (b) Storage Temp. : -40°C to +125°C (on Board).
- (c) Storage Condition (Component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity : 60% RH

5. Electrical Characteristics:

Part Number	Impedance 1 (Ω)± 25% @25MHz	Impedance 2 (Ω)± 25% @100MHz	DCR (mΩ) Max.	Rated Current (A) Typ.	
				ΔT=40°C	ΔT=60°C
Z323023W5400	23.0	40.0	0.60	21.0(1) 15.0(2)	26.0(1) 18.0(2)

6. Characteristics Curve:



NOTE: Specifications subject to change without notice. Please check our website for latest information.



7. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

7-2 Solder Wave:

Wave soldering is perhaps the most rigorous of surface mount soldering processes due to the steep rise in temperature seen by the circuit when immersed in the molten solder wave. Due to the risk of thermal damage to products, wave soldering of large size products is discouraged. Recommended temperature profile for wave soldering is shown in Figure 2.

7-3 Soldering Iron (Figure 3):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- a) Preheat circuit and products to 150°C.
- b) 350°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4-5 sec.

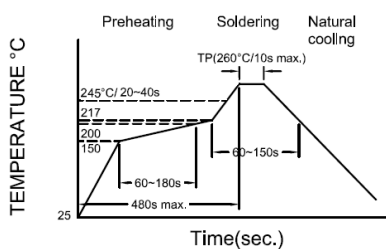


Figure 1. : Re-flow Soldering time 3 times Max.

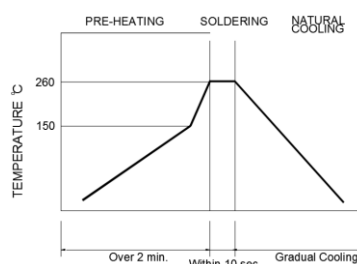


Figure 2. : Wave Soldering

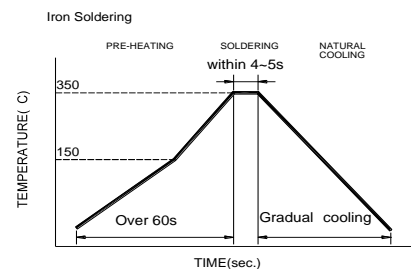


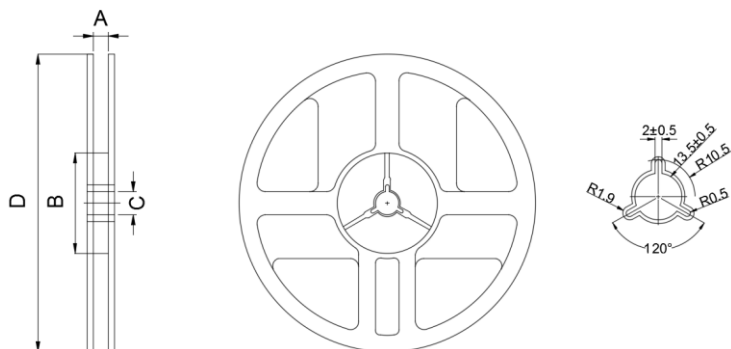
Figure 3. : Iron Soldering time 1 times Max.

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8. Packaging Information:

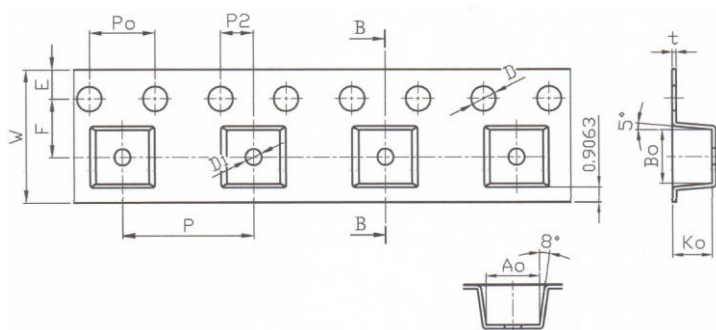
8-1 Reel Dimension



7"x12mm

Type	A(mm)	B(mm)	C(mm)	D(mm)
7"×12mm	13.5±0.5	60.0±2.0	13.5±0.5	178.0±2.0

8-2 Tape Dimension



Size	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	D1(mm)
		12.0±0.1	8.00±0.1	1.75±0.1	5.50±0.05	2.00±0.05	1.50+0.1/-0
Z323023	Po(mm)	Ao(mm)	Bo(mm)	Ko(mm)	t(mm)	10Po(mm)	
	4.00±0.1	3.50±0.1	3.35±0.1	2.40±0.1	0.30±0.05	40.0±0.20	

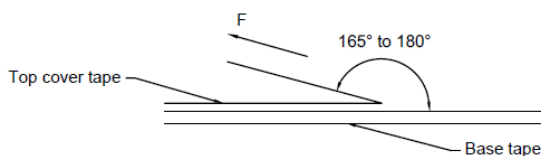
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8-3 Packaging Quantity

Chip Size	Z323023
Chip/Reel	1000
Inner Box	4000
Middle Box	20000
Carton	40000

8-4 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized

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